

WHAT IS CLAIMED:

1. A device for performing a master processing operation on a selected substrate, the device comprising:

a base substrate;

an adhesive carrier substrate having an inner surface facing the base substrate;

a layer of pressure-sensitive adhesive provided on the inner surface of the adhesive carrier substrate;

a release liner separating the base substrate from the adhesive carrier substrate, the release liner being folded along a fold line extending in a transversely extending direction to define two portions one of which is an activating portion;

the release liner having an outer surface facing the inner surface of the adhesive carrier substrate and an inner surface of the base substrate, the outer surface being a release surface;

the base substrate being separable from the release liner and the adhesive carrier substrate to enable the selected substrate to be positioned in a master processing position;

the activating portion enabling the master processing operation to be performed with the selected substrate in the master processing position by pulling the activating portion of the release liner in an activating direction generally perpendicular to the transverse direction and generally parallel to the base substrate and the selected substrate so as to progressively remove the release liner from the adhesive carrier substrate and cause the pressure-sensitive adhesive to adhere to the selected substrate and any peripheral portions of the base substrate extending adjacent the periphery of the selected substrate.

2. A device according to claim 1, wherein the base substrate includes a pressure-sensitive adhesive on the inner surface thereof.

3. A device according to claim 2, wherein the pressure-sensitive adhesive on the inner surface of the base substrate is a repositionable pressure-

sensitive adhesive adapted for repositionably adhering the selected substrate in the master processing position during the master processing operation.

4. A device according to claim 3, wherein the repositionable adhesive is provided as a strip extending transversely across the base substrate.

5. A device according to claim 1, wherein the outer surface of the release liner is coated with a release material.

6. A device according to claim 1, wherein the activating portion includes a tab extending out from between the base substrate and the adhesive carrier substrate when the base substrate and the adhesive carrier substrate are together in parallel relation for facilitating manual grasping and pulling thereof.

7. A device according to claim 6, wherein the activating portion is tapered toward the tab.

8. A device according to claim 1, wherein the activating portion includes a string extending out from between the base substrate and the adhesive carrier substrate when the base substrate and the adhesive carrier substrate are together in parallel relation for facilitating manual grasping and pulling thereof.

9. A device according to claim 1, the base substrate and the adhesive carrier substrate are joined at edges thereof and wherein the release liner has a stiffness such that, when the adhesive carrier substrate and release liner are folded apart from the base substrate so that each of the adhesive carrier and base substrates are laid on a planar surface, a portion of the release liner adjacent the fold line thereof will delaminate from the adhesive carrier substrate and stand out, thus enabling the master processing operation to be thereafter performed with the selected substrate in the master processing position on the base substrate by pulling the activating portion in the activating direction so as to progressively remove the release liner from the adhesive

carrier substrate and progressively pull the adhesive carrier substrate over and into contact with the base substrate and the selected substrate.

10. A device according to claim 1, wherein the base substrate is a transparent or translucent laminating film.

11. A device according to claim 1, wherein the adhesive carrier substrate is a transparent or translucent laminating film.

12. A device according to claim 1, wherein both the base substrate and the adhesive carrier substrate are transparent or translucent laminating films.

13. A device according to claim 1, wherein the adhesive carrier substrate is a magnetic substrate.

14. A device according to claim 13, wherein the base substrate is a transparent or translucent laminating film and wherein the inner surface of the base substrate has an affinity for bonding with the pressure-sensitive adhesive.

15. A device according to claim 1, wherein the adhesive carrier substrate is an adhesive transfer substrate and the inner surface thereof is a release surface.

16. A device according to claim 15, wherein the base substrate is a mask substrate and the inner surface thereof has an affinity for bonding with the pressure-sensitive adhesive.

17. A device according to claim 1, wherein the base substrate and the adhesive carrier substrate are each rectangular.

18. A method for performing a master processing operation on a selected substrate, the method comprising:

providing a device comprising:

(i) a base substrate,  
(ii) an adhesive carrier substrate having an inner surface facing the base substrate,  
(iii) a layer of pressure-sensitive adhesive provided on the inner surface of the adhesive carrier substrate, and  
(iv) a release liner separating the base substrate from the adhesive carrier substrate, the release liner having a release surface engaging the layer of pressure-sensitive adhesive;  
separating the base substrate from the release liner and the adhesive carrier substrate to enable the selected substrate to be positioned in a master processing position;  
positioning the selected substrate in the master processing position; and  
with the selected substrate in the master processing position, pulling the release liner in an activating direction generally parallel to the base substrate and the selected substrate so as to progressively remove the release liner from the adhesive carrier substrate and cause the pressure-sensitive adhesive to adhere to the selected substrate and any peripheral portions of the base substrate extending adjacent the periphery of the selected substrate.

19. A method according to claim 18, wherein:

the release liner is folded along a fold line extending in a transverse direction generally perpendicular to the activating direction to define two portions one of which is an activating portion,

the release liner has an outer surface facing the inner surface of the adhesive carrier substrate and an inner surface of the base substrate, the outer surface being the release surface, and

pulling the release liner in the activating direction is performed by pulling the activating portion of the release liner.

20. A method according to claim 19, wherein the base substrate includes a pressure-sensitive adhesive on the inner surface thereof and wherein positioning the selected substrate in the master processing position includes

adhering the selected substrate to the pressure-sensitive adhesive on the inner surface of the base substrate.

21. A method according to claim 20, wherein the pressure-sensitive adhesive on the inner surface of the base substrate is a repositionable pressure-sensitive adhesive adapted for repositionably adhering the selected substrate in the laminating position during the master processing operation, and wherein adhering the selected substrate to the pressure-sensitive adhesive on the inner surface of the base substrate includes repositionably adhering the selected substrate to the repositionable pressure-sensitive adhesive.

22. A method according to claim 21, wherein the repositionable adhesive is provided as a strip extending transversely across the base substrate and wherein repositionably adhering the selected substrate to the repositionable pressure-sensitive adhesive includes engaging the selected substrate with the strip.

23. A method according to claim 19, wherein the activating portion includes a tab extending out from between the base substrate and the adhesive carrier substrate for facilitating manual grasping and pulling thereof;

wherein the method further comprises bringing the adhesive carrier substrate, the release liner, the selected substrate and the base substrate together into parallel relation with the selected substrate in the master processing position between the release liner and the base substrate prior to pulling the activating portion; and

wherein pulling the activating portion of the release liner in the activating direction includes manually grasping and pulling the tab.

24. A method according to claim 19, wherein the activating portion includes a string extending out from between the base substrate and the adhesive carrier substrate for facilitating manual grasping and pulling thereof;

wherein the method further comprises bringing the adhesive carrier substrate, the release liner, and the base substrate together into parallel

relation with the selected substrate in the master processing position between the release liner and the base substrate prior to pulling the activating portion;

wherein pulling the activating portion of the release liner in the activating direction includes manually grasping and pulling the string.

25. A device according to claim 19 wherein separating the base substrate from the release liner and the adhesive carrier substrate includes folding the adhesive carrier substrate and the release liner apart from the base substrate so that each of the base and adhesive carrier substrates are laid on a planar surface, the release liner having a stiffness such that a portion thereof adjacent the fold line thereof will thereby delaminate from the adhesive carrier substrate and stand out;

wherein the positioning the selected substrate in the master processing position includes positioning the selected substrate on the folded apart base substrate; and

wherein the pulling the activating portion in the activating direction progressively removes the release liner from the adhesive carrier substrate and progressively pulls the adhesive carrier substrate over and into contact with the base substrate and the selected substrate.

26. A method according to claim 25, wherein the delamination and stand out of the portion of the release liner adjacent the fold line thereof exposes adhesive on the adhesive carrier substrate adjacent a nip defined where the adhesive carrier and base substrates are joined; and

wherein positioning the selected substrate on the folded apart base substrate includes engaging an edge of the selected substrate with the exposed adhesive.